

COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					△				
△					△				
APPLICABLE STANDARD									
RATING	OPERATING TEMPERATURE RANGE	-35 °C TO +85 °C(NOTE1)			STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE3)			
	OPERATING MOISTURE RANGE	20 %TO 80 %(NOTE2)			STORAGE MOISTURE RANGE	40 %TO 70 %(NOTE3)			
	CURRENT	1 A			VOLTAGE	150 V AC(DC)			
SPECIFICATIONS									
ITEM		TEST METHOD			REQUIREMENTS			QT AT	
CONSTRUCTION									
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT			ACCORDING TO DRAWING			×	×
MARKING		CONFIRMED VISUALLY.						×	×
ELECTRIC CHARACTERISTICS									
CONTACT RESISTANCE		100 mA (DC OR 1000 Hz).			30 mΩ MAX.				
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD.		20 mV MAX, 1mA (DC OR 1000Hz)						×	—
INSULATION RESISTANCE		100 V DC.			500 MΩ MIN.			×	—
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FLASHOVER OR BREAKDOWN.			×	—
MECHANICAL CHARACTERISTICS									
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.			① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			① NO ELECTRICAL DISCONTINUITY OF 1 μs.			×	—
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
ENVIRONMENTAL CHARACTERISTICS									
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 →5 TO 35 →+85 →5 TO 35°C TIME 30 →10 TO 15 →30 →10 TO15min UNDER 5 CYCLES.			① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN.			×	—
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 ~ 95 %, 96 h.			③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS			×	—
RESISTANCE TO SOLDERING HEAT		(1) REFLOW SOLDERING 《REFLOW AREA》 MAX 250°C WITHIN 10 sec. MIN 230°C WITHIN 60 sec 《PREHEATING AREA》 170°C to 190 °C 60 sec. To 120 sec. PUT THROUGH IN REFLOW FURNACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. (2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350 ± 5°C, FOR 5 ± 1 sec. NO STRENGTH ON CONTACT.			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			×	—
SOLDERABILITY		SOLDERING TEMPERATURE : 235 ± 5°C DURATION OF IMMERSION : SOLDERING, FOR 3 sec.			A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.			×	—
REMARKS					DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NON-CONDENSING NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.					<i>F. Matsumoto</i>	<i>S. Nakayama</i>	<i>T. Miyazaki</i>	<i>T. Miyazaki</i>	
Unless otherwise specified, refer to JIS C 5402					03.3.17	03.3.17	03.03.25	03.03.25	
Note QT:Qualification Test AT:Assurance Test ×:Applicable Test									
HRS HIROSE ELECTRIC CO., LTD.					SPECIFICATION SHEET			PART NO. DF14- * P-1.25H(55)	
CODE NO.(OLD)		DRAWING NO.			PART NO.			1 1	
CL		ELC4-160307-17			CL538-				

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